PACKAGE DESCRIPTION

Please refer to http://www.linear.com/designtools/packaging/ for the most recent package drawings.

LGA Package 35-Lead (11.25mm \times 6.25mm \times 2.82mm) (Reference LTC DWG # 05-08-1805 Rev B)

11.250 2.72 - 2.92aaa Z HX [Y BSC MOLD SUBSTRATE 6.250 BSC 0.27 - 0.37 2.40 - 2.60Z DETAIL A PAD 17 CORNER 4 PACKAGE TOP VIEW DETAIL A PACKAGE SIDE VIEW 8.890 SEE NOTES PADS BSC SEE NOTES 0.605 - 0.665/3\ 2.540 1.270 0.605 - 0.6655.080 BSC 0.0000 3 1.270 **BSC** PAD 1 C (0.30) Н G D С В PACKAGE BOTTOM VIEW

TOP VIEW 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

SUGGESTED PCB LAYOUT

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 LAND DESIGNATION PER JESD MO-222, SPP-010 AND SPP-020

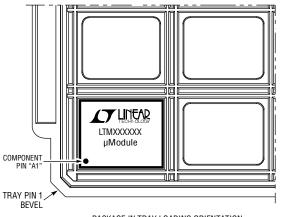
DETAILS OF PAD #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
THE PAD #1 IDENTIFIER MAY BE EITHER A MOLD OR A MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. THE TOTAL NUMBER OF PADS: 35

PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG $\mu Module$ PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

SYMBOL	TOLERANCE
aaa	0.15
bbb	0.10



PACKAGE IN TRAY LOADING ORIENTATION

8021fd

LGA 35 0113 REV B

